

10-02-2002

FORM PTO-1594  
(Rev. 6-93)

ET

U.S. DEPARTMENT  
OF COMMERCEAtty Docket #:  
ONS00363

102239323

Patent and  
Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

## 1. Name of conveying part(ies):

Josef Halamik  
Frantisek Sukup

9.25-02

Additional name(s) of conveying party(ies) is provided on attached sheet.

## 3. Nature of conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other \_\_\_\_\_

Execution date of  
conveyance:

September 20, 2002

## 2. Name and address of receiving party(ies):

SEMICONDUCTOR COMPONENTS INDUSTRIES, L.L.C. of  
5005 East McDowell Road, Phoenix, AZ 85018

Additional name(s) &amp; address(es) attached?

☐ Yes☒ No

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

September 20, 2002

## A. Patent Application No.(s):

10/254274

## B. Patent No.(s):

Additional numbers attached?

☐ Yes☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **SEMICONDUCTOR COMPONENTS INDUSTRIES, L.L.C.**Internal Address: Patent Administration - A700Street Address: P. O. Box 62890City, State, Zip: Phoenix, Arizona 85082-2890

## 6. Total number of applications and patents involved:

7. Total fee (37 C.F.R. 3.41)..... \$40.00☐ Enclosed☒ Authorized to be charged to deposit account8. Deposit account number: **501086**

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## 9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

James J. Stipanuk

44,358

Name of Person Signing

Reg. No.

Signature

Date

Total number of pages including cover sheet, attachments, and document: **3 (1 sheet double-sided)**

OMB No. 0651-0011 (exp. 4/94)

10/01/2002 BTOM11 00000065 501086 10254274

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PATENT  
REEL: 013336 FRAME: 0939

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we,

|                        |                              |
|------------------------|------------------------------|
| Name                   | of (City/State/Country)      |
| <b>Josef Halamik</b>   | ROZNOV P. R.; CZECH REPUBLIC |
| <b>Frantisek Sukup</b> | ZASOVA; CZECH REPUBLIC       |

have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto Semiconductor Components Industries, LLC (SCI), a corporation of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States of America in and to certain inventions relating to improvements in  
**METHOD OF FORMING A VOLTAGE DETECTION DEVICE AND STRUCTURE THEREFOR**

(Attorney Docket No. ONS00363),

described, illustrated, and claimed in an application for Letters Patent of the United States of America executed by us, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation, or reissue thereof.

We hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and we further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of

their respective countries to SCI.

We agree that, when requested, we will, without charge to SCI, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in SCI, its successors, assigns, and legal representatives or nominees.

We covenant with SCI, its successors, assigns, and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Signed and Witnessed on (date):

20/September/2002

By (inventor signature):

Josef Halamik  
Josef Halamik

Witness by (signature):

Ivo Velez

Printed Name of Witness:

Ivo Velez

Signed and Witnessed on (date):

20/September/2002

By (inventor signature):

Frantisek Sukup  
Frantisek Sukup

Witness by (signature):

Antoni Rosypal

Printed Name of Witness:

Antoni Rosypal